

Extreme Low Loss & High Tg & Ultra low CTE & Halogen Free
NY8888N / NY8888NP

特点 FEATURES:

- 低介电常数和低介质损耗 (Low Dk 3.4@10GHz, Low Df 0.0014@10GHz)
- 优异的电气和热可靠性 Excellent electrical and thermal reliability properties
- 优异的防潮性和无铅回流焊工艺兼容 Excellent moisture resistance and lead Free reflow process compatible
- 优越的PTH可靠性和耐CAF能力 Superior PTH reliability and anti-CAF capability
- 高Tg及超低热膨胀系数 High Tg and ultra-low thermal expansion coefficient

应用领域 APPLICATIONS:

- 数据中心 Data Centre
- AI服务器 AI Server
- 高性能计算机 High Performance Computer
- 超级核心路由器和交换机 Super Core Router and Switcher

NY8888N基板典型性能 Typical Properties for NY8888N Laminate

属性 Property	项目 Item		测试方法 IPC-TM-650	测试条件 Test Condition	单位 Unit	典型值 Typical Value	
热性能 Thermal	玻璃态转换温度 Tg		2.4.25	DSC	℃	\	
			2.4.24	TMA	℃	180	
			2.4.24.4	DMA	℃	220	
	X/Y轴热膨胀系数,X/Y-axis Expansion		2.4.24.5	< Tg,TMA	PPM/℃	10/11	
	Z轴热膨胀系数 Z-axis Expansion		2.4.24	< Tg,TMA	PPM/℃	50	
				> Tg,TMA	PPM/℃	150	
			2.4.24	50~260℃	%	1.8	
	热裂解温度 Td		2.4.24.6	TGA(5%W.L)	℃	400	
	耐热性 T288		2.4.24.1	Clad	Min	> 120	
Etched				Min	> 120		
电性能 Electrical	介电常数 DK (R/C:65%)	1MHz	2.5.5.9	C-24/23/50	-	\	
		1GHz					\
		10GHz				SPDR method	3.4
	介质损耗 Df (R/C:65%)	1MHz	2.5.5.9	C-24/23/50	-	\	
		1GHz					\
		10GHz				SPDR method	0.0014
	体积电阻 Volume Resistivity		2.5.17.1	C-96/35/90	MΩ-cm	2.4×10 ⁹	
	表面电阻 Surface Resistivity				MΩ	1.9×10 ⁸	
	物理性能 Physical	吸水率 Water Absorption		2.6.2.1	E-1/105+D-24/23	%	0.06
剥离强度 Peel Strength (HTE)		1oz	2.4.8	As Received	N/mm	\	
剥离强度 Peel Strength (RTF)		1oz				\	
剥离强度 Peel Strength (HVLP)		1oz				0.6	
弯曲强度 Flexural Strength		Warp	2.4.4	As Received	N/mm ²	200	
		Fill				180	
阻燃性 Flame Resistance		UL-94	A&E-4/125	-	V-0		